



Material Content Data Sheet



Sales Product Name		BTS7030-2EPA		Issued		4. July 2019			
MA#		MA005345015							
Package		PG-TSDSO-14-22		Weight*		64.99 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.139	1.75	1.75	17519	17519	
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		145		
	non noble metal	zinc	7440-66-6	0.038	0.06		580		
	non noble metal	iron	7439-89-6	0.754	1.16		11602		
wire	non noble metal	copper	7440-50-8	30.617	47.11	48.34	471089	483416	
	non noble metal	copper	7440-50-8	0.489	0.75	0.75	7530	7530	
	encapsulation	organic material	carbon black	1333-86-4	0.087	0.13		1343	
encapsulation	plastics	epoxy resin	-	3.404	5.24		52376		
	inorganic material	silicondioxide	60676-86-0	25.603	39.39	44.76	393936	447655	
leadfinish	non noble metal	tin	7440-31-5	1.642	2.53	2.53	25259	25259	
plating	noble metal	silver	7440-22-4	0.816	1.26	1.26	12556	12556	
glue	plastics	epoxy resin	-	0.069	0.11		1061		
	noble metal	silver	7440-22-4	0.325	0.50	0.61	5004	6065	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com